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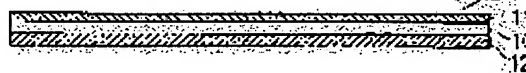
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(54) LAMINATE MANUFACTURING METHOD AND MULTILAYERED PRINTED WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method for efficiently manufacturing a laminate suitable for a build-up method under such a condition that an adhesive layer has sufficient adhesiveness, and a multilayered printed wiring board using the laminate.

SOLUTION: The laminate is manufactured by laminating a metal foil 1 to one surface of a polymeric film 10 through a first adhesive layer 11 and laminating a second thermosetting adhesive layer 12 to the other surface of the polymeric film 10. Alternatively, an adhesive is applied to both surfaces of the polymeric film 10 to be dried to bring the adhesive layers on both surfaces of the polymeric film 10 to a semicured state and the metal foil 13 is laminated to the adhesive layer 11 on the single surface under a condition capable of holding the adhesive layers on both surfaces to the semicured state.



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## LEGAL STATUS

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